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L. Spruell

Inventor(s): Tae Heon Lee et al.

U.S. Serial Number: 09/687,048

U.S. Filing Date: October 13, 2000

Title of Invention: LEADFRAME AND
SEMICONDUCTOR PACKAGE
WITH IMPROVED SOLDER
JOINT STRENGTH

Docket Number: 45475-00026

Commissioner for Patents
Washington, D.C. 20231

CERTIFICATE OF MAILING

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Dear Madam or Sir:

PROPOSED AMENDMENTS TO THE DRAWINGS

It is respectfully requested that the Examiner approve the following amendments to the Drawings of the above-identified application for patent:

1. ☒ Please approve the changes to the Drawings as indicated in red ink on the attached drawing sheet(s).
2. ☐ Please substitute the attached Formal Figures for the Informal Figures as originally filed.
3. ☐ Please add new Figure(s) for the Informal Figures to the application.

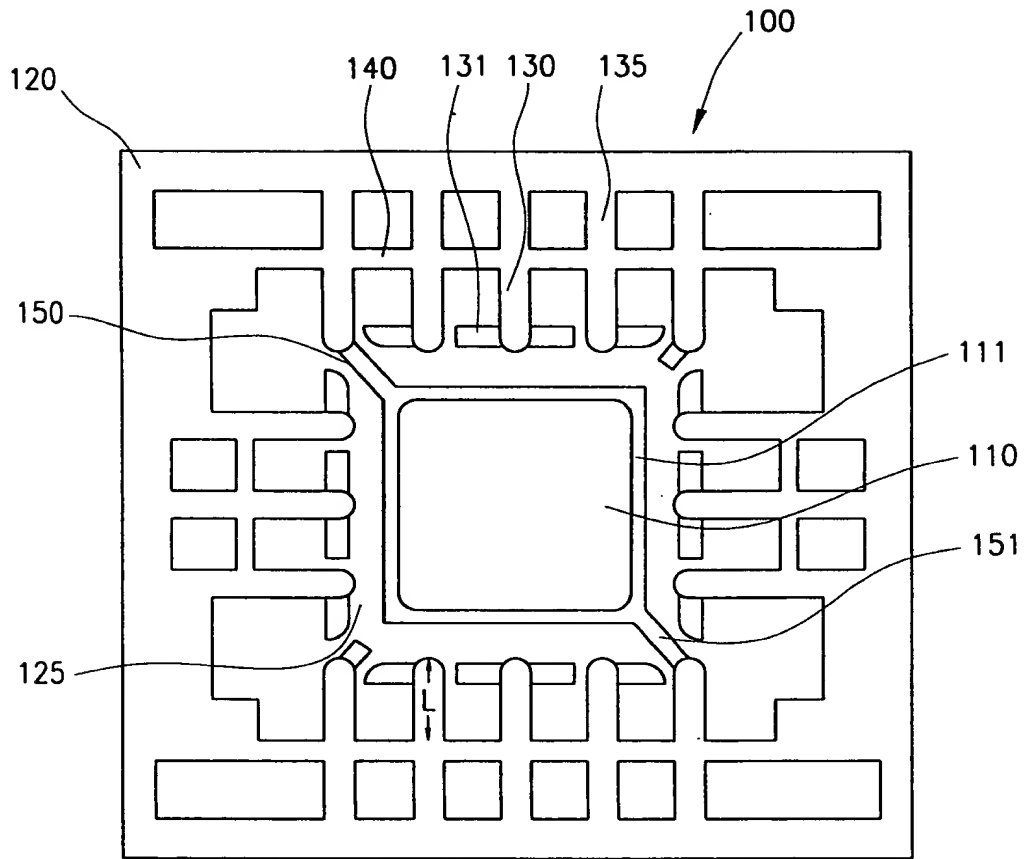


FIG. 1
(PRIOR ART)



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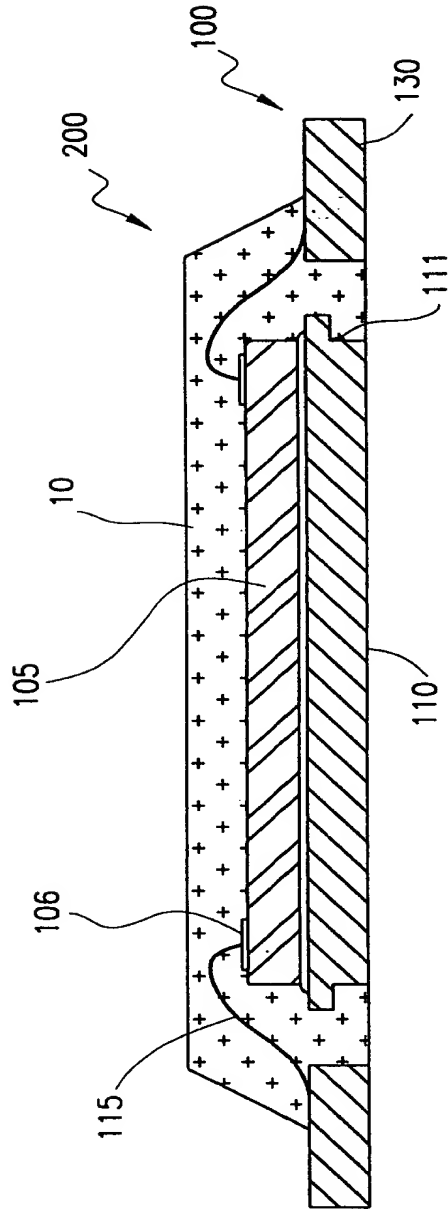


FIG. 2
(PRIOR ART)



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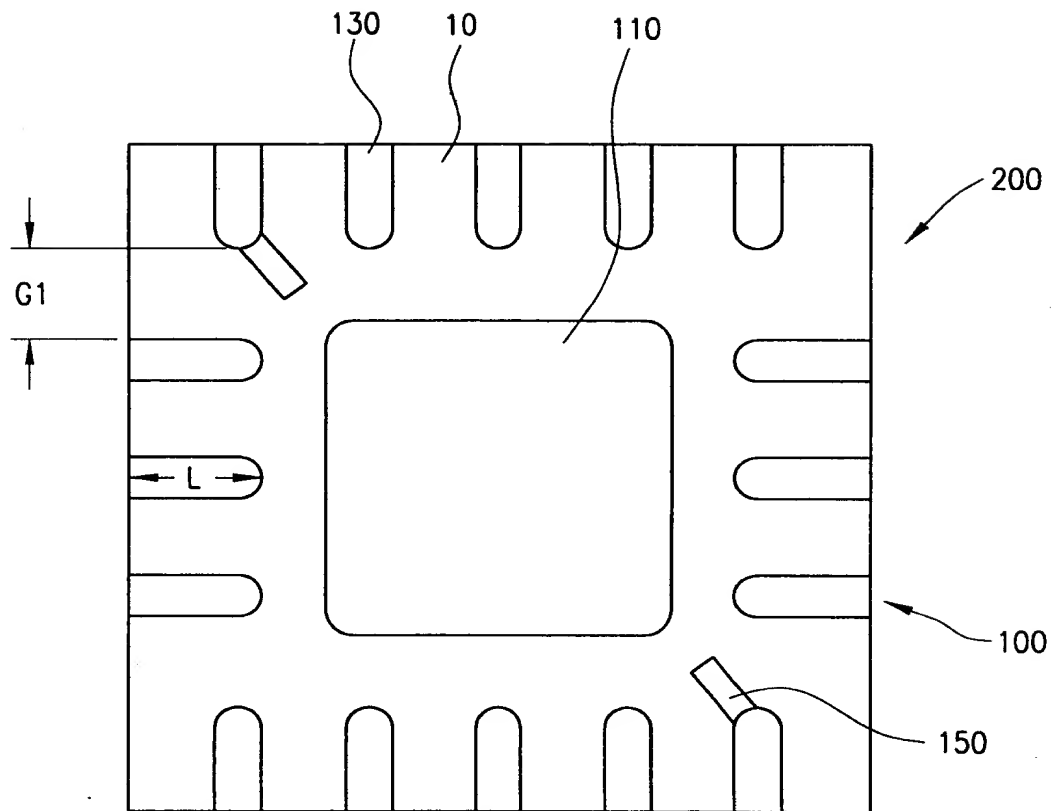


FIG. 3
(PRIOR ART)



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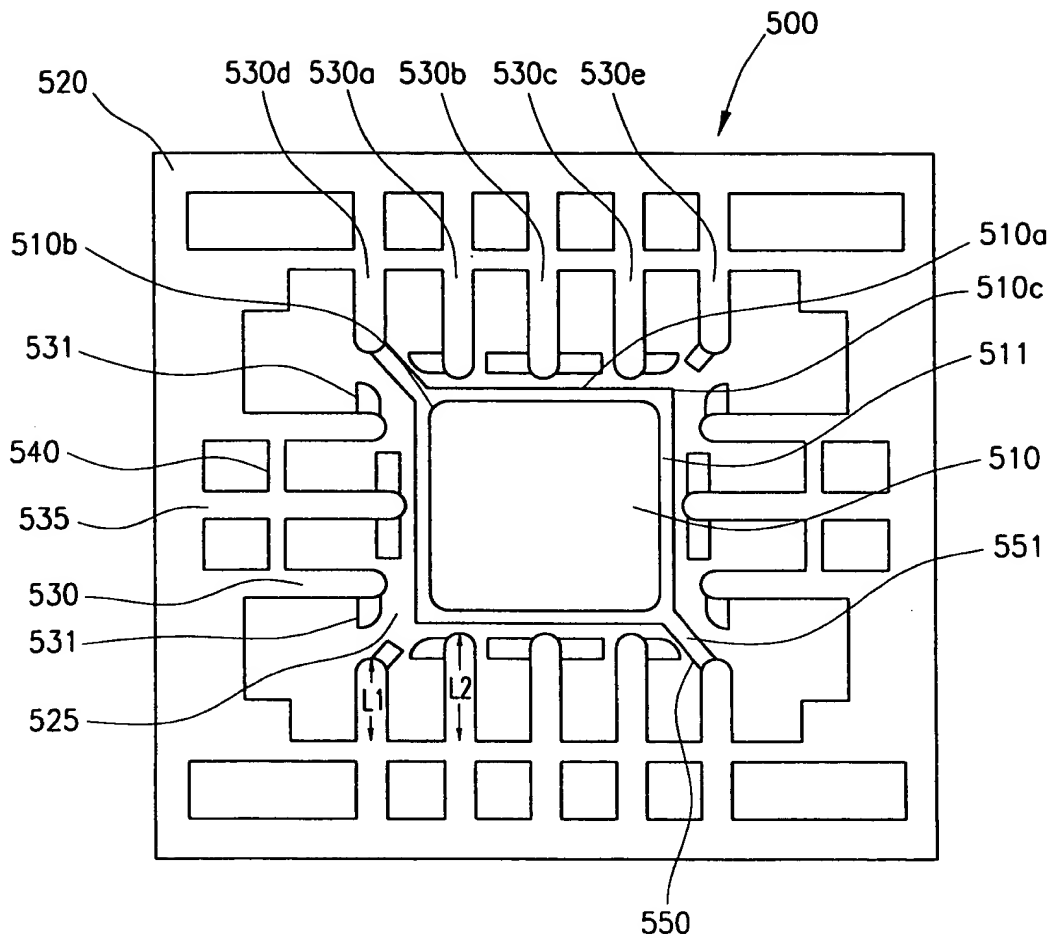


FIG. 4

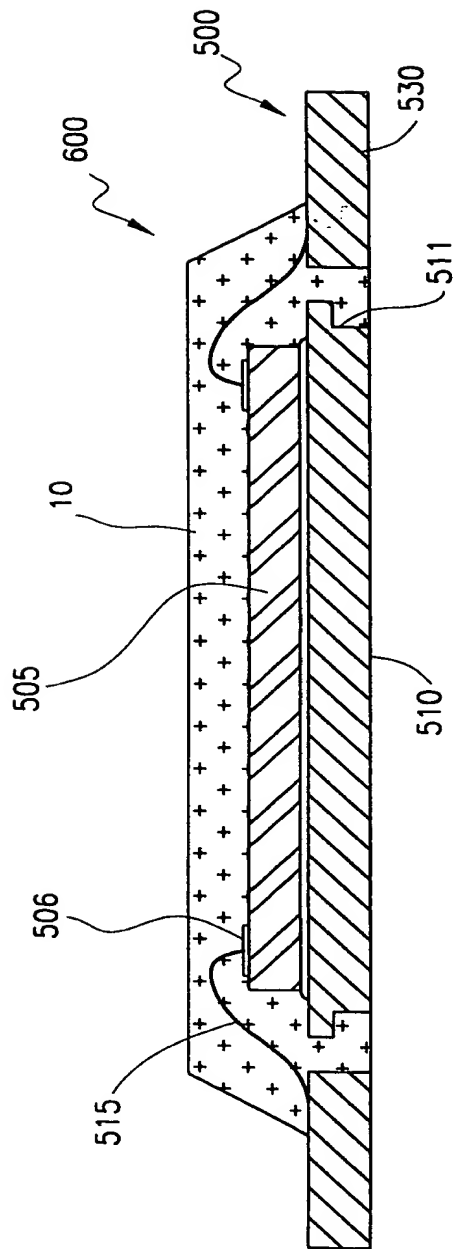


FIG. 5

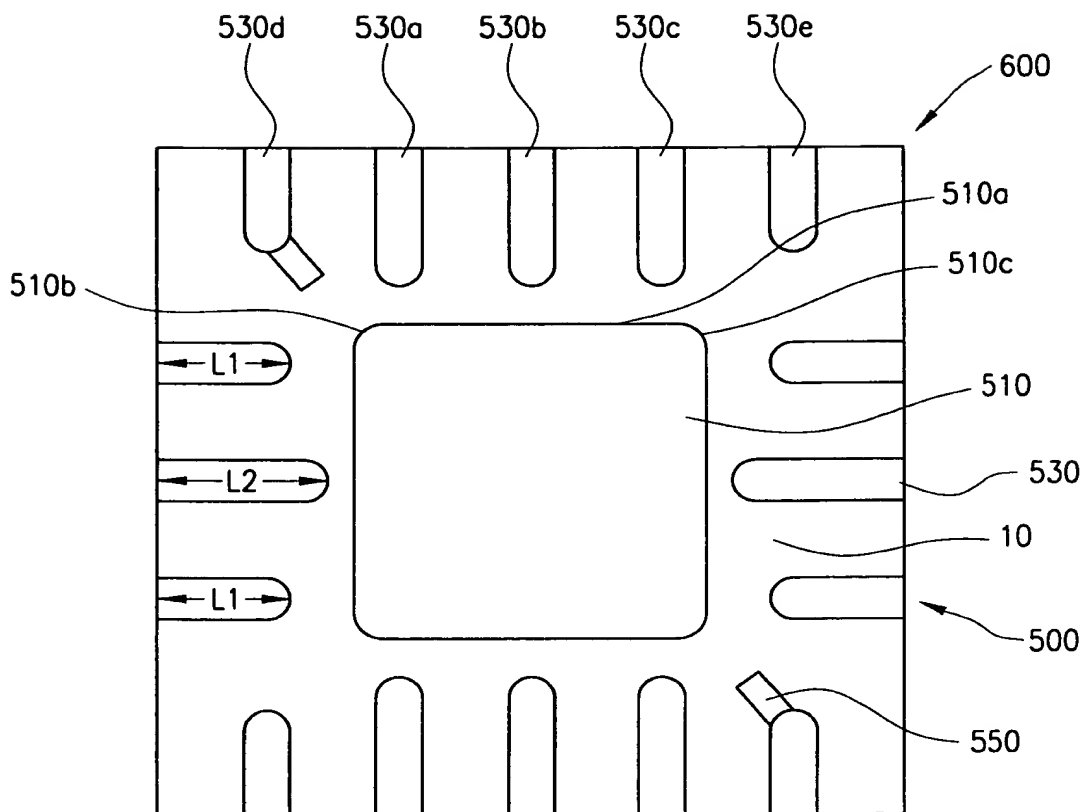


FIG. 6

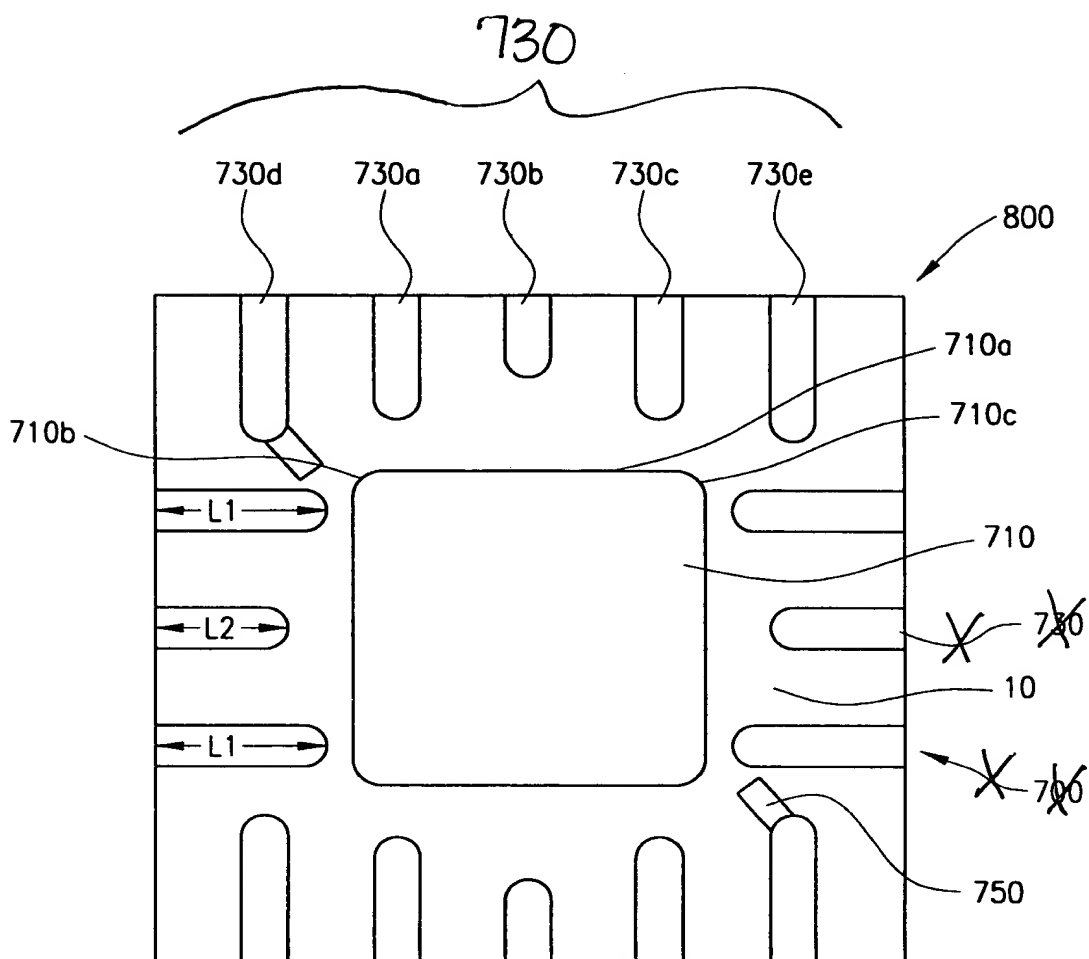


FIG. 7